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A B S T R A C T

A semiconductor processing apparatus includes
a port structure for transferring a target substrate
(W) therethrough. A partition wall (4) separates
5 an exterior area (S1) and an interior area (S2) from
each other, and has a port (41) for transferring the
target substrate (W) therethrough. A door (43) is
disposed on the partition wall (4) and configured to
open and close the port (41). A mount portion (61) is
10 disposed in the exterior area (S1) in front of the port
(41). A pressing member (72) is disposed above the
mount portion (61). The pressing member (72) presses
down a carrier container (2) for target substrates (W)
against the mount portion (61). The pressing member
15 (72) is moved between a lower position to engage with
the carrier container (2) and an upper position not to
interfere with transfer of the carrier container (2).